

Dual Differential Comparators

Check for Samples: LM193, LM293, LM293A, LM393, LM393A, LM2903, LM2903V

FEATURES

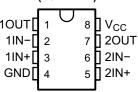
- Single Supply or Dual Supplies
- Wide Range of Supply Voltage
 - Max Rating: 2 V to 36 V
 - Tested to 30 V: Non-V Devices
 - Tested to 32 V: V-Suffix Devices
- Low Supply-Current Drain Independent of Supply Voltage: 0.4 mA (Typ) Per Comparator
- Low Input Bias Current: 25 nA (Typ)
- Low Input Offset Current: 3 nA (Typ) (LM139)
- Low Input Offset Voltage: 2 mV (Typ)
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

DESCRIPTION

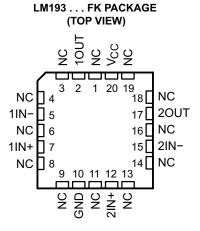
These devices consist of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and $V_{\rm CC}$ is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM193 is characterized for operation from -55°C to 125°C. The LM293 and LM293A are characterized for operation from -25°C to 85°C. The LM393 and LM393A are characterized for operation from 0°C to 70°C. The LM2903 is characterized for operation from -40°C to 125°C.





NC - No internal connection





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

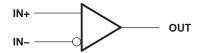




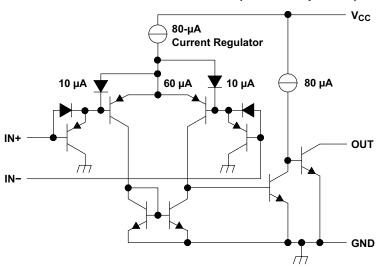
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Symbol (Each Comparator)



Schematic (Each Comparator)



COMPONENT	COUNT
Epi-FET	1
Diodes	2
Resistors	2
Transistors	30

Current values shown are nominal.



TEXAS INSTRUMENTS

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
Supply voltage, V _{CC} ⁽²⁾		36	V
Differential input voltage, V _{ID} ⁽³⁾		±36	V
Input voltage range (either input), V _I		-0.3 to 36	V
Output voltage, V _O		36	V
Output current, I _O		20	mA
Duration of output short circuit to ground (4)		Unlimited	
	D package	97	
	DGK package	172	
Package thermal impedance, junction to free air, $\theta_{JA}^{(5)(6)}$	P package	85	°C/W
	PS package	95	
	PW package	149	
Package thermal impedance, junction to case, $\theta_{JC}^{(7)(8)}$	FK package	5.61	°C/W
Package thermal impedance, junction to case, θ_{JC}	JG package	14.5	10/00
Operating virtual-junction temperature, T _J		150	°C
Case temperature for 60 s	FK package	260	°C
Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package	300	°C
Storage temperature range, T _{stg}	·	-65 to 150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to network ground.

(3) Differential voltages are at IN+ with respect to IN-.

(4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

(6) The package thermal impedance is calculated in accordance with JESD 51-7.

(8) The package thermal impedance is calculated in accordance with MIL-STD-883.

⁽⁵⁾ Maximum power dissipation is a function of T_J (max), θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J \text{ (max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

⁽⁷⁾ Maximum power dissipation is a function of T_J (max), θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J \text{ (max)} - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.



Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	T _A ⁽¹⁾	LM	193		LM: LM:			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
		$V_{CC} = 5 \text{ V to } 3$		25°C		2	5		2	5	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR} min$ $V_{O} = 1.4 V$,	Full range			9			9	mV
	Input offset current	V _O = 1.4 V		25°C		3	25		5	50	nA
I _{IO}	input onset current	V _O = 1.4 V		Full range			100			250	ΠA
	Input bias current	V _O = 1.4 V		25°C		-25	-100		-25	-250	nA
I _{IB}	input bias current	V _O = 1.4 V		Full range			-300			-400	IIA
V	Common-mode input-voltage			25°C	0 to V _{CC} - 1.5			$V_{CC} - 1.5$			V
V _{ICR}	range ⁽²⁾			Full range	0 to V _{CC} - 2			0 to V _{CC} - 2			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V},$ $V_{O} = 1.4 \text{ V to}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to}$		25°C	50	200		50	200		V/mV
	High lovel output ourrent	V _{OH} = 5 V	V _{ID} = 1 V	25°C		0.1			0.1	50	nA
I _{OH}	High-level output current	V _{OH} = 30 V	V _{ID} = 1 V	Full range			1			1	μA
V	Law level autout valtage	1 4 55 4	\/ 1 \/	25°C		150	400		150	400	mV
V _{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700			700	IIIV
I _{OL}	Low-level output current	V _{OL} = 1.5 V,	$V_{ID} = -1 V$	25°C	6			6			mA
	Cumply ourrent	R₁ = ∞		25°C		0.8	1		0.8	1	mA
I _{CC}	Supply current	IXL = ~	V _{CC} = 30 V	Full range			2.5			2.5	ША

⁽¹⁾ Full range (MIN or MAX) for LM193 is -55°C to 125°C, for LM293 is 25°C to 85°C, and for LM393 is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽²⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC}+ – 1.5 V for the inverting input (–), and the non-inverting input (+) can exceed the V_{CC} level; the comparator provides a proper output state. Either or both inputs can go to 30 V without damage.





Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST (CONDITIONS	T _A ⁽¹⁾	LM29 LM39			UNIT
					MIN	TYP	MAX	j l
.,	land offertualte as	V _{CC} = 5 V to 30 V,	V _O = 1.4 V	25°C		1	2	mV
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR(min)}$	0	Full range			4	mv
	land offer to consist	V 4.4.V		25°C		5	50	- ^
I _{IO}	Input offset current	V _O = 1.4 V		Full range			150	nA
I Innut biog gurrant		V 4.4.V		25°C		-25	-250	- 0
I _{IB}	Input bias current	V _O = 1.4 V		Full range			-400	nA
	(2)			25°C	0 to V _{CC} - 1.5			
V _{ICR}	Common-mode input-voltage range ⁽²⁾			Full range	0 to V _{CC} - 2			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CO}$		25°C	50	200		V/mV
	High level output ourrent	V _{OH} = 5 V,	$V_{ID} = 1 V$	25°C		0.1	50	nA
I _{OH}	High-level output current	$V_{OH} = 30 V,$	$V_{ID} = 1 V$	Full range			1	μA
V	Low-level output voltage	I _{OL} = 4 mA,	V _{ID} = -1 V	25°C		150	400	mV
V_{OL}	Low-level output voltage	I _{OL} = 4 IIIA,	$v_{ID} = -1 \ v$	Full range			700	IIIV
I_{OL}	Low-level output current	V _{OL} = 1.5 V,	$V_{ID} = -1 V$,	25°C	6			mA
	Supply current	D	V _{CC} = 5 V	25°C		0.8	1	
I _{CC}	(four comparators)	R _L = ∞	V _{CC} = 30 V	Full range			2.5	mA

⁽¹⁾ Full range (MIN or MAX) for LM293A is 25°C to 85°C, and for LM393A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽²⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V without damage.



Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	DADAMETED	TEST COM	DITIONS	T (1)	LM2	2903		LM29	903A		UNIT	
	PARAMETER	TEST CON	DITIONS	T _A ⁽¹⁾	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
		$V_{CC} = 5 \text{ V to MAX}^{(2)}$,		25°C		2	7		1	2		
V _{IO}	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{IC} = V_{ICR(min)},$		Full range			15			4	mV	
	Input offset current	V _O = 1.4 V		25°C		5	50		5	50	nA	
I _{IO}	input onset current	V _O = 1.4 V		Full range			200			200	IIA	
	Input bias current	V _O = 1.4 V		25°C		-25	-250		-25	-250	nA	
I _{IB}	input bias current	V _O = 1.4 V		Full range			-500			-500	IIA	
	Common-mode input-			25°C	0 to V _{CC} -1.5			0 to V _{CC} - 1.5			V	
V _{ICR}	voltage range ⁽³⁾			Full range	0 to V _{CC} - 2			0 to V _{CC} - 2				
A _{VD}	Large-signal differential- voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1.4 \text{ N}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$	/ to 11.4 V,	25°C	25	100		25	100		V/mV	
	High-level output current	$V_{OH} = 5 V$,	$V_{ID} = 1 V$	25°C		0.1	50		0.1	50	nA	
I _{OH}	nigri-level output current	$V_{OH} = V_{CC} MAX^{(2)},$	$V_{ID} = 1 V$	Full range			1			1	μA	
.,	Laur laural austrust violtage	Ι 4 το Λ	V _{ID} = -1 V,	25°C		150	400		150	400	mV	
V _{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$v_{ID} = -1 \ v$	Full range			700			700	IIIV	
I _{OL}	Low-level output current	V _{OL} = 1.5 V,	$V_{ID} = -1 V$	25°C	6			6			mA	
	Cumply augrent	D	V _{CC} = 5 V	25°C		0.8	1		0.8	1		
I _{CC}	Supply current	R _L = ∞	V _{CC} = MAX	Full range			2.5			2.5	mA	

⁽¹⁾ Full range (MIN or MAX) for LM2903 is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

Switching Characteristics

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST COND	LM2901, LM293, LM293A LM393, LM393A LM2903	UNIT		
		TYP			
	R_L connected to 5 V through 5.1 k Ω ,	100-mV input step with 5-mV overdrive	1.3		
Response time	$C_L = 15 \text{ pF}^{(1)(2)}$	TTL-level input step	0.3	μs	

⁽¹⁾ C_L includes probe and jig capacitance.

⁽²⁾ V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.

⁽³⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V (32 V for V-suffix devices) without damage.

⁽²⁾ The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

SLCS005X - OCTOBER 1979-REVISED JULY 2013





REVISION HISTORY

CI	hanges from Revision W (July 2010) to Revision X	Page
•	Updated document to new TI data sheet format - no specification changes.	1
•	Updated Features.	1
•	Added ESD warning.	2
•	Removed Ordering Information table.	2

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity AO

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM193DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903QDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903VQPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM293ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

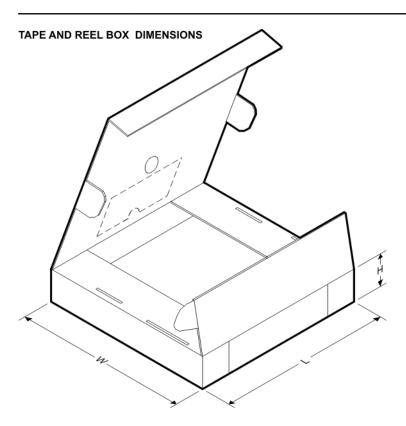


PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393APSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

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*All dimensions are nomina

All dimensions are nominal	Dookses Type	Dookowa Drawina	Dina	CDO	Longth (mm)	Midth (mm)	Uniabt (mm)
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM193DR	SOIC	D	8	2500	367.0	367.0	35.0
LM2903DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DR	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	367.0	367.0	35.0
LM2903DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM2903PSR	SO	PS	8	2000	367.0	367.0	38.0
LM2903PWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903QDRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM2903VQPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
LM293ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM293ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM293ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM293ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM293ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM293DR	SOIC	D	8	2500	364.0	364.0	27.0
LM293DR	SOIC	D	8	2500	367.0	367.0	35.0
LM293DR	SOIC	D	8	2500	340.5	338.1	20.6
LM293DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM293DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393ADR	SOIC	D	8	2500	364.0	364.0	27.0
LM393ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM393ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393APSR	SO	PS	8	2000	367.0	367.0	38.0
LM393APWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393DR	SOIC	D	8	2500	367.0	367.0	35.0
LM393DR	SOIC	D	8	2500	340.5	338.1	20.6
LM393DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM393DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393PSR	SO	PS	8	2000	367.0	367.0	38.0
LM393PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0

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